

# Sync SRAM Code Information(1/2)

Last Updated : Nov. 2012

**S 7 X X X X X X X X - X X X X X X X X**  
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

**(1) Netsol Memory : S**

**(2) Sync SRAM : 7**

**(3) Functional Mode**

- A : Sync Pipelined Burst
- B : Flow Through
- H : Double Data Rate I, Common I/O
- I : Double Data Rate II, Common I/O
- J : Double Data Rate II, Separate I/O
- K : Double Data Rate II+, Common I/O
- L : Double Data Rate II+, Common I/O with ODT
- M : NTSRAM + Flow Through
- N : NTSRAM + Sync Pipelined Burst
- Q : Quadruple SRAM I
- R : Quadruple SRAM II
- S : Quadruple SRAM II+
- T : Quadruple SRAM II+ with ODT

**(4) ~ (5) Density**

- |              |              |
|--------------|--------------|
| 40 : 4M~4.5M | 80 : 8M~9M   |
| 16 : 16M~18M | 32 : 32M~36M |
| 64 : 64M~72M | 44 : 144M    |
| 28 : 288M    | 57 : 576M    |
| 1G : 1G      |              |

**(6) ~ (7) Organization**

- |           |          |
|-----------|----------|
| 08 : x8   | 09 : x9  |
| 18 : x18  | 32 : x32 |
| 36 : x36  | 72 : x72 |
| 44 : x144 |          |

**(8) ~ (9) Vcc, Interface, Mode**

- 30 : 2.5V/3.3V Wide, LVTTTL, 2E1D
- 31 : 2.5V/3.3V Wide, LVTTTL, 2E2D
- 35 : 2.5V/3.3V Wide, LVTTTL, SB-FT
- 62 : 2.5V/1.8V, HSTL, Burst2
- 64 : 2.5V/1.8V, HSTL, Burst4
- 82 : 1.8V, HSTL, Burst2
- 84 : 1.8V, HSTL, Burst4
- T2 : 1.8V, 2clock latency, Burst2
- T4 : 1.8V, 2clock latency, Burst4
- U2 : 1.8V, 2.5clock latency, Burst2
- U4 : 1.8V, 2.5clock latency, Burst4

**(10) Generation**

- |                    |                    |
|--------------------|--------------------|
| M : 1st Generation | A : 2nd Generation |
| B : 3rd Generation | C : 4th Generation |

**(11) “—”**

# Sync SRAM Code Information(2/2)

Last Updated : Nov. 2012

**S 7 X X X X X X X X - X X X X X X X X**  
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

## (12) Package

- P : TQFP(LF)
- Q : TQFP
- E : FBGA(LF)
- F : FBGA
- G : PBGA(LF)
- H : PBGA
- LF means Lead Free

## (13) Temp

- A : Automotive (-40°C ~ +125°C)
- I : Industrial (-40°C ~ +85°C)
- C : Commercial (0°C ~ +70°C)

## (14)~(15) Speed

- SPB, NT-SPB, DDR,  
 DDR- I/ II/ II+, Quadruple- I/ II/ II+
- 13 : 133MHz                      16 : 166MHz
- 20 : 200MHz                      25 : 250MHz
- 30 : 300MHz                      33 : 333MHz
- 40 : 400MHz                      45 : 450MHz
- 50 : 500MHz                      55 : 550MHz
- 60 : 600MHz                      65 : 650MHz
- 66 : 666MHz                      70 : 700MHz
- 75 : 750MHz
- FT, NT-FT
- 60 : 6.0ns                          65 : 6.5ns
- 70 : 7.0ns                          75 : 7.5ns
- 80 : 8.0ns                          85 : 8.5ns
- 90 : 9.0ns                          10 : 10ns

**\* Note**

- (1) ~ (14) : customer ordering code, appears on top of PKG**
- (16) ~ (18) : code for Labeling, appears on label on Box**

## (16) Packing "Packing Type Reference"

Marking	Packing Type
0 (Number)	Tray, Tube
T	Tape & Reel

## (17)~(18) Special code for customer demand

00 : default

# Async SRAM Code Information

Last Updated : Nov. 2012

**S 6 X X X X X X X X - X X X X X X X X**  
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

**(1) Netsol Memory : S**

**(2) Async SRAM : 6**

**(3) Functional Mode**

R : Fast SRAM

**(4) ~ (5) Density**

40 : 4M                      80 : 8M  
 16 : 16M                    32 : 32M  
 64 : 64M

**(6) ~ (7) Organization**

04: x4                      08 : x8  
 16 : x16

**(8) Vcc**

C : 5.0V                    V : 3.3V  
 U : 3.0V                    S : 2.5V

**(9) Mode**

1 : CS Low Active  
 2 : CS1, CS2 - Chip Select Signal  
 3 : CS1, CS2, CS3 - Chip Select Signal

**(10) Generation**

M : 1st Generation      A : 2nd Generation  
 B : 3rd Generation      C : 4th Generation

**(11) “—”**

**(12) Package**

U : 44TSOP2(LF)      Y : 48TSOP1(LF)

**(13) Temp**

A : Automotive (-40°C ~ +125°C)  
 I : Industrial (-40°C ~ +85°C)  
 C : Commercial (0°C ~ +70°C)

**(14)~(15) Speed (tAA)**

08 : 8ns                      09 : 9ns  
 10 : 10ns                    12 : 12ns

**(16) Packing “Packing Type Reference”**

Marking	Packing Type
0 (Number)	Tray, Tube
T	Tape & Reel

**(17)~(18) Special code for customer demand**

00 : default

**\* Note**

**(1) ~ (14) : customer ordering code, appears on top of PKG**

**(16) ~ (18) : code for Labeling, appears on label on Box**

# Wafer/Chip Code Information

Last Updated : Nov. 2012

**S 6 X X X - X X - X X X X X X X X**  
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16

**(1) Netsol Memory : S**

**(2) Async SRAM : 6**

**(3) Functional Mode**

R : Fast SRAM

**(4) ~ (5) Density**

40 : 4M

16 : 16M

64 : 64M

80 : 8M

32 : 32M

**(6) “—”**

**(7) Mode**

1 : CS Low Active

2 : CS1, CS2 - Chip Select Signal

3 : CS1, CS2, CS3 - Chip Select Signal

**(8) Generation**

M : 1st Generation

A : 2nd Generation

B : 3rd Generation

C : 4th Generation

**(9) “—”**

**(10) Product form**

W : Wafer

C : Chip

**(11) Test Level**

1 : Hot Temp, DC sort

2 : Hot Temp, DC and selected AC sort

3 : Ho and Cold Temp,  
DC and selected AC sort

**(12)~(16) Code for Labeling**

**(13)~(16) Special code for customer demand**

0000 : default

**\* Note**

**(1) ~ (11) : customer ordering code**

**(12) ~ (16) : code for Labeling, appears on label on Box**